

metal Bond Blades

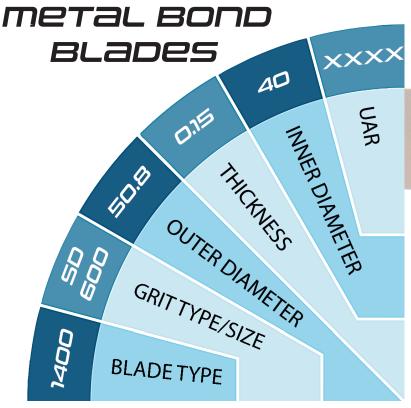
1400 SERIES



APPLICATIONS

QFN, BGA, FR4/PCB, resin boards, composite materials, polymers and softer ceramics

diamonds that are bonded together using a sintered metal powder. This means they offer blade wear and blade life characteristics in between that of fast wearing blades (resin-bonded) and low wearing blades (electroformed or nickel bonded). Metal bond blades largely maintain their profile and diameter making them an excellent choice for volume electronics applications where productivity and low cost of ownership is key.



BLADE TYPE	GRIT TYPE/SIZE	OUTER DIAMETER	THICKNESS	INNER DIAMETER	UAR
1400 Metal Bonded	SD- Synthetic diamond 3000 - 2/6um 2000 - 4/8um 1500 - 5/10um 1200 - 6/12um 1000 - 8/16um 800 - 10/20um 700 - 12/25um 600 - 20/30um 500 - 30/40um 400 - 40/60um	50 - 110mm	0.05 - 0.70mm	40mm	UAR- Unique Application Reference, - unique code that incorporates a number of parameters to suit your application. *

* Options available on bond type, concentration and additive ingredients

Loadpoint Expertise

Our customers trust Loadpoint to help them develop class-leading products. We have helped many customers develop task orientated solutions for ultrasound scanners, inkjet printers, SAW filters, MEMS devices and a whole range of silicon based products.

Micromachining solutions for:

SEMICONDUCTORS OPTICAL

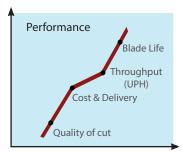
ELECTRONICS MEDICAL/ULTRASOUND

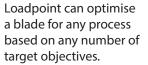
FERRO-ELECTRONICS SOLAR OPTO-ELECTRONICS SONAR

Loadpoint Blade Ranges

- Resin Blade
- Hubbed Blade
- Resin on steel core
- Electroformed Blade
- Metal Blade
- Vitrified Blade

Blade Optimisation Program





Let us know your dicing challenges and we will put together a program to enhance your process.

